EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	573	parallel with (substrate plate) same (via through adj hole) and flip adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:36
L2	34	parallel with (substrate plate) same (via through adj hole) same flip adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:22
L3	9	2 and (filter grating)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:17
L4	106	("4776661" | "5061027" | "5101460" | "5164930" | "5193130" | "5200631" | "5237434" | "5266794" | "5268985" | "5276748" | "5295208" | "5410622" | "5412743" | "5419762").PN. OR ("5568574").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 09:11
L5	75	4 and (filter grating)	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 09:11
L6	113	(distance space) near5 "between" near5 (substrate plate) and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:14
L7	4	6 and (distance space) near5 "between" near5 (substrate plate) with (".mu." micron)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:17
L8	1	6 and 3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:15

L9	171	flip adj chip near2 package and (input output) same (filter grating)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:21
L10	0	9 and (distance space) near5 "between" near5 (substrate plate) with (".mu." micron)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:18
L11	11	9 and (distance space) near5 "between" near5 (substrate plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:21
L12	13889	(input output) same fiber same (substrate plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:21
L13	5643	flip adj chip near2 package	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:39
L14	51	12 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:21
L16	16	14 and (substrate plate) same (via through adj hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:49
L17	5	16 and optic$4 same filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:31

L18	424	flip adj chip same align$5 same (fiber filter grating)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:31
L19	87	flip adj chip with align$5 with (fiber filter grating)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:34
L20	33	19 and (substrate plate) same (via through adj hole) and flip adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:32
L21	6	flip adj chip with align$5 with (fiber and (filter grating))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:34
L22	9	1 and (solder reflow$3) same align$5 same (optical adj element)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:37
L23	9	22 and (filter fiber)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:38
L24	7	22 and (filter)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:38
L25	0	flip adj chip near2 package and align$5 with (fiber) with filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:40

L26	16	flip adj chip near2 package and align$5 same (fiber) same filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:44
L27	25	(solder bump bond flip adj chip c4) same align$4 with fiber with filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:45
L28	0	(solder adj (bump bond) flip adj chip c4) same align$4 with fiber with filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:46
L29	41	(solder adj (bump bond) flip adj chip c4) and align$4 with fiber with filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:46
L30	6	14 and (substrate plate) same (via through adj hole) near10 fill$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/03/19 09:49
L31	11	("20010023979" | "20020102060" | "20020113958" | "20020118924" | "20020164113" | "20020175339" | "5463229" | "6127736" | "6396116" | "6450699" | "6571466").PN. OR ("6825065").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 10:17
L32	14	l26 and (solder bump) same metal	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 10:22
L33	5413	flip adj chip and (solder bump) same metal same (tin nickel copper silver gold)	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 10:25
L34	4971	flip adj chip and (solder bump) same metal same (tin and nickel copper silver gold)	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 10:26

L35	481	flip adj chip and (solder bump) same metal same (tin and nickel and copper and silver and gold)	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 10:26
L36	6	35 and optical same alignment	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/19 10:26